

5A Avg.

65 Volts

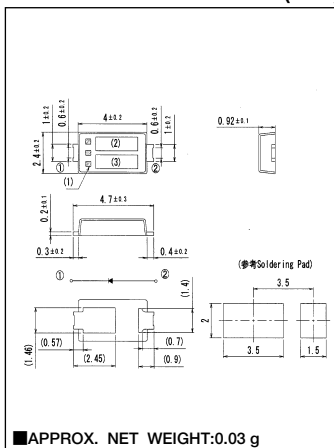
SBD

NA05QSA065

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	65	V
平均整流電流 Average Rectified Forward Current	I_O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	$T_a=27^{\circ}\text{C}^*$ $V_{RM}=30\text{V}$ 1.3 A
			$T_l=92^{\circ}\text{C}$ T:lead Temperature $V_{RM}=30\text{V}$ 5.0 A
実効順電流 R.M.S. Forward Current	$I_F(\text{RMS})$	7.85	A
サージ順電流 Surge Forward Current	I_{FSM}	100 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^{\circ}\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^{\circ}\text{C}$

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.03 g

■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}\text{C}, V_{RM}=65\text{V}$	—	—	400	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}\text{C}, I_{FM}=5\text{A}$	—	—	0.61	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient * ガラエポ基板実装	—	—	130	$^{\circ}\text{C}/\text{W}$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	13	$^{\circ}\text{C}/\text{W}$

* プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 2.0 × 1.5 mm, 2.0 × 3.5 mm)

■定格・特性曲線

